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(74) Agent: **PENILLA, Albert, S.**; Martine Penilla & Gencarella, LLP, 710 Lakeway Drive, Suite 200, Sunnyvale, CA 94085 (US).

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(71) Applicant (*for all designated States except US*): **LAM RESEARCH CORPORATION** [US/US]; 4650 Cushing Parkway, Fremont, CA 94538 (US).

(72) Inventors; and

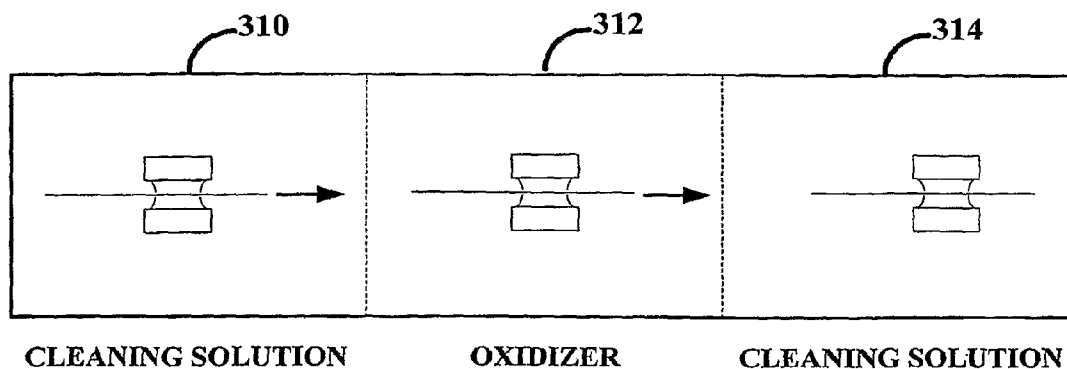
(75) Inventors/Applicants (*for US only*): **ZHU, Ji** [CN/US]; 3101 Carlson Blvd., Apt.4, El Cerrito, CA 94530 (US). **YUN, Seokmin** [KR/US]; 2749 Foxglove Ct., Pleasanton, CA 94588 (US). **WILCOXSON, Mark** [US/US]; 6942 Colton Blvd., Oakland, CA 94611 (US). **DE LARIOS, John, M.** [US/US]; 941 Loma Verde, Palo Alto, CA 94303 (US).

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(54) Title: POST ETCH WAFER SURFACE CLEANING WITH LIQUID MENISCUS



(57) Abstract: A method for cleaning the surface of a semiconductor wafer is disclosed. A first cleaning solution is applied to the wafer surface to remove contaminants on the wafer surface. The first cleaning solution is removed with some of the contaminants on the wafer surface. Next, an oxidizer solution is applied to the wafer surface. The oxidizer solution forms an oxidized layer on remaining contaminants. The oxidizer solution is removed and then a second cleaning solution is applied to the wafer surface. The second cleaning solution is removed from the wafer surface. The cleaning solution is configured to substantially remove the oxidized layer along with the remaining contaminants.